



August 1997

4-Channel Wideband and Video Multiplexer

| F | Features | |
|---|--------------------|--------|
| • | Crosstalk (10MHz) | <-60dB |
| • | Fast Access Time | 150ns |
| • | Fast Settling Time | 200ns |
| • | TTL Compatible | |

Applications

- · Wideband Switching
- Radar
- TV Video
- ECM

Ordering Information

| PART NUMBER | TEMP. RANGE (^O C) | PACKAGE | PKG. NO. |
|----------------|----------------------------------|--------------|----------|
| HI1-0524-5 | 0 to 75 | 18 Ld CERDIP | F18.3 |
| HI1-0524-2 | -55 to 125 | 18 Ld CERDIP | F18.3 |
| HI4P0524-5 | 0 to 75 | 20 Ld PLCC | N20.35 |
| HI3-0524-5 | 0 to 75 | 18 Ld PDIP | E18.3 |
| HI1-0524-8 | -55 to 125 | 18 Ld CERDIP | F18.3 |
| HI1-0524/883 | -55 to 125 | 18 Ld CERDIP | F18.3 |
| HI4-0524/883 | -55 to 125 | 20 Ld CLCC | J20.A |

Description

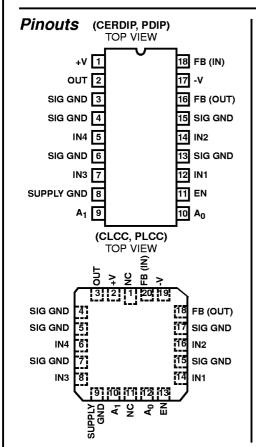
The HI-524 is a 4-Channel CMOS analog multiplexer designed to process single-ended signals with bandwidths up to 10MHz. The chip includes a 1 of 4 decoder for channel selection and an enable input to inhibit all channels (chip select).

Three CMOS transmission gates are used in each channel, as compared to the single gate in more conventional CMOS multiplexers. This provides a double barrier to the unwanted coupling of signals from each input to the output. In addition, Dielectric Isolation (DI) processing helps to insure the Crosstalk is less than -60dB at 10MHz.

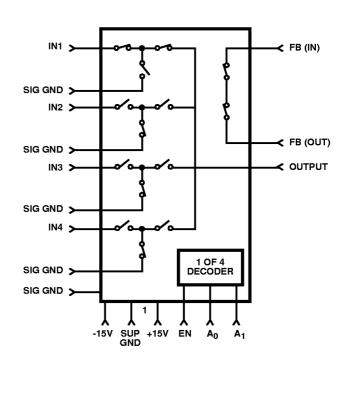
The HI-524 is designed to operate into a wideband buffer amplifier such as the Harris HA-2541. The multiplexer chip includes two "ON" switches in series, for use as a feedback element with the amplifier. This feedback resistance matches and tracks the channel $r_{\mbox{ON}}$ resistance, to minimize the amplifier $V_{\mbox{OS}}$ and its variation with temperature.

The HI-524 is well suited to the rapid switching of video and other wideband signals in telemetry, instrumentation, radar and video systems.

For MIL-STD-883 compliant parts, request the HI-524/883 data sheet



Functional Diagram



Absolute Maximum Ratings Thermal Information θ_{JA} (°C/W) θ_{JC} (°C/W) Thermal Resistance (Typical, Note 1) Digital Input Voltage CERDIP Package 65 16 90 N/A Analog Input Voltage PLCC Package 80 N/A +V_{IN}+V_{SUPPLY} +2.0V -V_{IN}....--V_{SUPPLY} -2.0V PLCC, PDIP Packages150°C Maximum Storage Temperature **Operating Conditions** (PLCC)....-65°C to 150°C Temperature Range HI-524-2, -8....-55°C to 125°C Maximum Lead Temperature (Soldering, 10s) 300°C (PLCC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications Supplies = +15V, -15V; V_{AH} (Logic Level High) = +2.4V, V_{AL} = (Logic Level Low) = +0.5V; V_{EN} = +2.4V, Unless Otherwise Specified

| | TEST | TEMP | HI-524-2/-8 | | | HI-524-5 | | | |
|--|--|------|-------------|------|-----|----------|------|-----|-------|
| PARAMETER CONDITIONS | | (°C) | MIN | TYP | MAX | MIN | TYP | MAX | UNITS |
| SWITCHING CHARACTERISTICS | | | • | • | • | | • | • | |
| Access Time, t _A | (Note 5) | 25 | - | 150 | 300 | - | 150 | 300 | ns |
| Break-Before-Make Delay, t _{OPEN} | (Note 5) | 25 | - | 20 | - | - | 20 | - | ns |
| Enable Delay (ON), $R_L = 500\Omega$, t_{ON} (EN) | | 25 | - | 180 | 300 | - | 180 | - | ns |
| Enable Delay (OFF), $R_L = 500\Omega$, t_{OFF} (EN) | | 25 | - | 180 | 250 | - | 180 | - | ns |
| Settling Time (0.1%) | (Note 5) | 25 | - | 200 | - | - | 200 | - | ns |
| (0.01%) | | 25 | - | 600 | - | - | 600 | - | ns |
| Crosstalk | (Note 6) | 25 | - | -65 | - | - | -65 | - | dB |
| Channel Input Capacitance, C _{S(OFF)} | | 25 | - | 4 | - | - | 4 | - | pF |
| Channel Output Capacitance, C _{D(OFF)} | | 25 | - | 10 | - | - | 10 | - | pF |
| Digital Input Capacitance, CA | | 25 | - | 5 | - | - | 5 | - | pF |
| DIGITAL INPUT SPECIFICATIONS | | | | | | | | | |
| Input Low Threshold (TTL), V _{AL} | | Full | - | - | 0.8 | - | - | 0.8 | ٧ |
| Input High Threshold (TTL), V _{AH} | | Full | 2.4 | - | - | 2.4 | - | - | ٧ |
| Input Leakage Current (High), I _{AH} | | Full | - | 0.05 | 1 | - | 0.05 | 1 | μΑ |
| Current (Low), A _L | | Full | - | - | 25 | - | - | 25 | μΑ |
| ANALOG CHANNEL SPECIFICATIONS | | | | | | | | | |
| Analog Signal Range, V _{IN} | | Full | -10 | - | +10 | -10 | - | +10 | ٧ |
| On Resistance, r _{ON} | (Note 2) | 25 | - | 700 | - | - | 700 | - | Ω |
| | l [| Full | - | - | 1.5 | - | - | 1.5 | ΚΩ |
| Off Input Leakage Current, IS (OFF) | (Note 3) | 25 | - | 0.2 | - | - | 0.2 | - | nA |
| | | Full | - | - | 50 | - | - | 50 | nA |
| Off Output Leakage Current, I _{D (OFF)} | (Note 3) | 25 | - | 0.2 | - | - | 0.2 | - | nA |
| | <u> </u> | Full | - | - | 50 | - | - | 50 | nA |
| On Channel Leakage Current, I _D (ON) | (Note 3) | 25 | - | 0.7 | - | - | 0.7 | - | nA |
| | [| Full | - | - | 50 | - | - | 50 | nA |

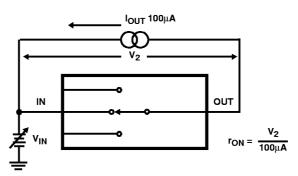
Electrical Specifications Supplies = +15V, -15V; V_{AH} (Logic Level High) = +2.4V, V_{AL} = (Logic Level Low) = +0.5V; V_{EN} = +2.4V, Unless Otherwise Specified (Continued)

| | TEST | ТЕМР | HI-524-2/-8 | | | HI-524-5 | | | |
|-----------------------------------|------------|------|-------------|-----|-----|----------|-----|-----|-------|
| PARAMETER | CONDITIONS | (°C) | MIN | TYP | MAX | MIN | TYP | MAX | UNITS |
| 3dB Bandwidth | (Note 4) | 25 | - | 8 | - | - | 8 | - | MHz |
| POWER SUPPLY CHARACTERISTICS | | | | | | | | | |
| Power Dissipation, P _D | | Full | - | - | 750 | - | - | 750 | mW |
| Current, I+ | (Note 7) | Full | - | - | 25 | - | - | 25 | mA |
| Current, I- | (Note 7) | Full | 1 | - | 25 | - | - | 25 | mA |

NOTES:

- 1. Absolute maximum ratings are limiting values, applied individually, beyond which the serviceability of the circuit may be impaired. Functional operation under any of these conditions is not necessarily implied.
- 2. V_{IN} = 0V; I_{OUT} = 100 μ A (See Test Circuit 1).
- 3. $V_O = \pm 10V$; $V_{IN} = \pm 10V$. (See Test Circuits 2, 3, 4.)
- 4. MUX output is buffered with HA-5033 amplifier.
- 5. 6V Step, ±3V to ±3V, See Test Circuit 5.
- V_{IN} = 10MHz, 3V_{P-P} on one channel, with any other channel selected. (Worst case is channel 3 selected with input on channel 4.) MUX output is buffered with HA-2541 as shown in Applications section. Terminate all channels with 75Ω.
- 7. Supply currents vary less than 0.5mA for switching rates from DC to 2MHz.

Typical Performance Curves and Test Circuits $T_A = 25^{\circ}C$, $V_{SUPPLY} = \pm 15V$, $V_{AH} = 2.4V$, $V_{AL} = 0.8V$, Unless Otherwise Specified



TEST CIRCUIT 1. ON RESISTANCE

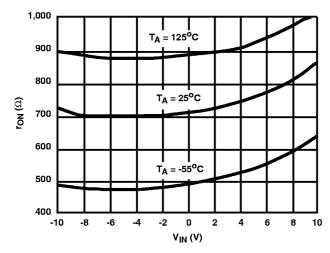


FIGURE 1. ON RESISTANCE vs ANALOG INPUT VOLTAGE

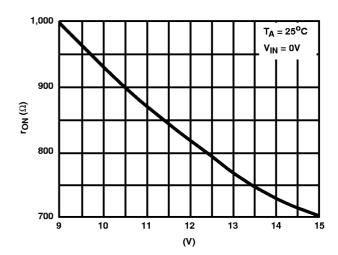


FIGURE 2. ON RESISTANCE vs SUPPLY VOLTAGE

$\textbf{\textit{Typical Performance Curves and Test Circuits}} \quad T_{A} = 25^{o}C, \ V_{SUPPLY} = \pm 15V, \ V_{AH} = 2.4V, \ V_{AL} = 0.8V, \ V_{AH} = 2.4V, \ V_{AH} = 2.4$

Unless Otherwise Specified (Continued)

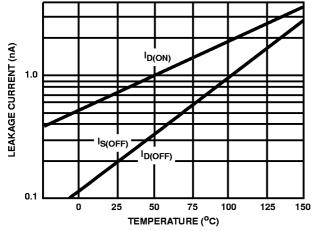
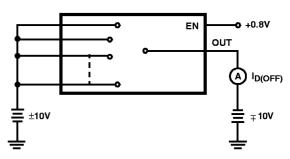
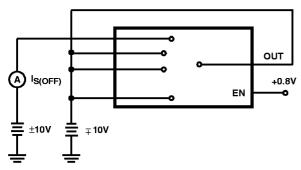


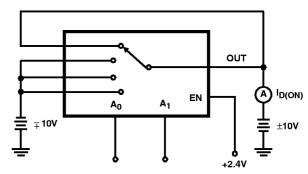
FIGURE 3. LEAKAGE CURRENT vs TEMPERATURE



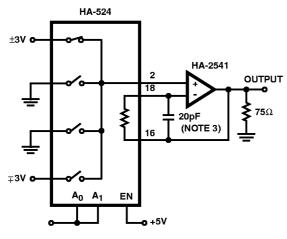
TEST CIRCUIT 2. LEAKAGE CURRENT (NOTE 1)



TEST CIRCUIT 3. LEAKAGE CURRENT (NOTE 1)



TEST CIRCUIT 4. LEAKAGE CURRENT (NOTE 1)



TEST CIRCUIT 5. SETTLING TIME, ACCESS TIME, BREAK-**BEFORE-MAKE DELAY (NOTE 2)**

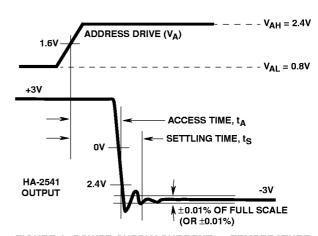


FIGURE 4. POWER SUPPLY CURRENT vs TEMPERATURE

NOTES:

- 1. Two measurements per channel: $\pm 10V$ and $\mp 10V$. (Two measurements per device for $I_{D(OFF)} \pm 10V$ and $\mp 10V$.)
- 2. This test requires channel inputs 1 and 4 at the same level.
- 3. Capacitor value may be selected to optimize AC performance.

Typical Performance Curves and Test Circuits T_A = 25°C, V_{SUPPLY} = ±15V, V_{AH} = 2.4V, V_{AL} = 0.8V, Unless Otherwise Specified **(Continued)**

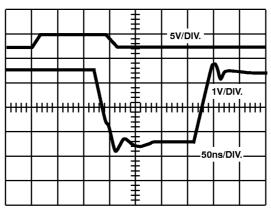


FIGURE 5. ACCESS TIME

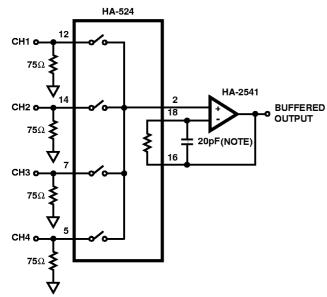
TABLE 1. TRUTH TABLE

| A ₁ | A ₀ | EN | ON CHANNEL |
|----------------|----------------|----|------------|
| X | Х | L | None |
| L | L | Н | 1 (Note) |
| L | Н | Н | 2 |
| Н | L | Н | 3 |
| Н | Н | Н | 4 |

NOTE: Channel 1 is shown selected in the Functional Diagram.

Typical Applications

Often it is desirable to buffer the HI-524 output, to avoid loading errors due to the channel "ON" resistance:



NOTE: Capacitor value may be selected to optimize AC performance. The buffer amplifier should offer sufficient bandwidth and slew rate to avoid degradation of the anticipated signals. For video switching, the HA-5033 and HA-2542 offer good performance plus ± 100 mA output current for driving coaxial cables. For

general wideband applications, the HA-2541 offers the convenience of unity gain stability plus 90ns settling (to $\pm 0.1\%$) and $\pm 10V$ output swing. Also, the HI-524 includes a feedback resistance for use with the HA-2541. This resistance matches and tracks the channel "ON" resistance, to minimize offset voltage due to the buffer's bias currents.

Note that the on-chip feedback element between pins 16 and 18 includes two switches in series, to simulate a channel resistance. These switches open for V_{EN} = Low. This allows two or more HI-524s to operate into one HA-2541, with their feedback elements connected in parallel. Thus, only the selected multiplexer provides feedback, and the amplifier remains stable.

All HI-524 DIP package pins labeled 'SIG GND' (pins 3, 4, 6, 13, 15) should be externally connected to signal ground for best crosstalk performance.

Bypass capacitors ($0.1\mu F$ to $1\mu F$) are recommended from each HI-524 supply pin to power ground (pins 1 and 17 to pin 8 DIP package). Locate the buffer amplifier near the HI-524 so the two capacitors may bypass both devices.

If an analog input 1V or greater is present when supplies are off, a low resistance is seen from that input to a supply line. (For example, the resistance is approximately 160Ω for an input of -3V.) Current flow may be blocked by a diode in each supply line, or limited by a resistor in series with each channel. The best solution, of course, is to arrange that no digital or analog inputs are present when the power supplies are off.

Die Characteristics

DIE DIMENSIONS:

2250μm x 3720μm x 485μm ±25μm

METALLIZATION:

Type: CuAl

Thickness: 16kÅ ±2kÅ

PASSIVATION:

Type: Nitride Over Silox Nitride Thickness: 3.5kÅ ±1kÅ Silox Thickness: 12kÅ ±2kÅ

WORST CASE CURRENT DENSITY:

1.58 x 10⁵ A/cm²

Metallization Mask Layout

HI-524

